

## WHAT IS CLAIMED IS

1. A light emitting diode packaging structure comprising:
  - a light emitting diode comprising a frame and a packaging portion packaging a portion of the frame, the frame comprising a primary support and first and second subsidiary supports on opposite sides of the primary support, a light-emitting chip having positive and negative poles being formed on the primary support; and
  - a rectification circuit comprised of diodes of low power high voltage construction, the diodes being formed on the first and second subsidiary supports respectively and electrically connected to the positive and negative poles of the light-emitting chip by leads.
2. The light emitting diode packaging structure as claimed in Claim 1, wherein the rectification circuit comprises a bridge circuit.
3. A light emitting diode packaging structure comprising:
  - a light emitting diode comprising a frame and a packaging portion packaging a portion of the frame, the frame comprising a primary support and first and second subsidiary supports on opposite sides of the primary support, a substrate having pre-defined positive and negative electrodes being formed on the primary support and a light-emitting chip having positive and negative poles being formed on the substrate with the positive and negative poles of the light-emitting chip corresponding to and connected to the positive and negative electrodes of the substrate; and

a rectification circuit comprised of diodes of low power high voltage construction, the diodes being formed on the substrate and electrically connected to the first and second subsidiary supports respectively by leads.

4. The light emitting diode packaging structure as claimed in Claim 3, wherein the rectification circuit comprises a bridge circuit.